



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 9938**
Hiroshi TAKANASHI et al. : **Docket No. 2001-0476**
Serial No. 09/838,118 : **Group Art Unit 1752**
Filed April 20, 2001 : **Examiner S. Lee**

NEGATIVE-WORKING PHOTSENSITIVE :
RESIN COMPOSITION AND PHOTSENSITIVE
RESIN PLATE USING THE SAME

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

RESPONSE

Assistant Commissioner for Patents,
Washington, D.C. 20231

Sir:


In response to the Official Action dated August 14, 2002, please amend the present
application as follows:

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IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Twice Amended) A photosensitive resin plate comprising a support having formed thereon directly or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a negative working photosensitive resin composition consisting essentially of

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- (A) a film-forming polymer,
 - (B) an unsaturated compound having a radical polymerizable ethylenic double bond,
 - (C) a photopolymerization initiator in an amount of 0.5 - 5 wt% based on the weight of the photosensitive resin composition components (A) to (E),
 - (D) a thermal polymerization inhibitor, and
 - (E) at least one member selected from compounds represented by following formula (I):